

Application Note

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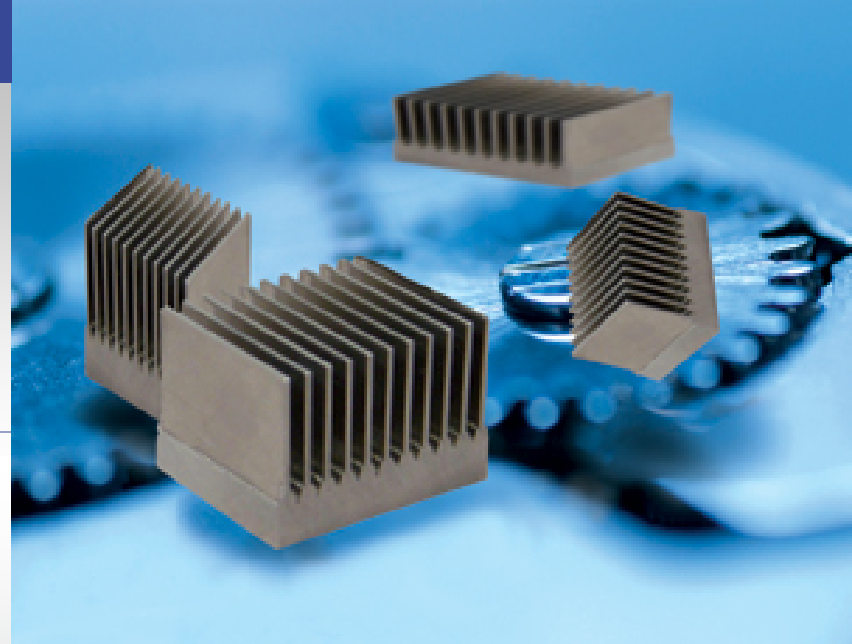
C³ = Cut Cost to Core™

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Bonded Fin Heatsink

Overview

With shrinking package sizes for today's electronics, many new designs require more efficient heatsinks than the traditional extruded product. This requires a heatsink with a high density of long thin fins to maximize cooling surface area. They may also require a copper base with aluminum fins to further boost efficiency but keep the cost lower than all copper. Bonded fin heatsinks are the only way to get these features.



Segue's Solution

Bonded fin heatsinks are an important part of Segue's full line of ThermTec thermal products. With over 30 years experience, our highly automated plant's patented assembly technique allows us to respond to customer's most demanding designs. Modern equipment, including in-house machining and surface treatment, assure high quality from the beginning to end of the process. Segue also offers complete assembly capabilities by mounting semiconductors, standoffs and fans for a total customer solution.

Applications

- Motor Controls
- High power audio equipment
- Uninterruptible power supplies (UPS)
- Welders
- Power Rectifiers
- High Output Power Supplies

Benefits

- Able to dissipate 2-3 times the heat of the same volume extruded heatsink
- Less expensive than a liquid cooled system
- Heatsink base and fins can be different materials to maximize efficiency
- Segue offers one stop shopping for heatsink, machining, and surface treatment
- High quality with very competitive pricing
- Segue can provide the complete heatsink assembly to maximize savings

